

Special Issue on Recent Advances in Chemical Mechanical Planarization/Polishing

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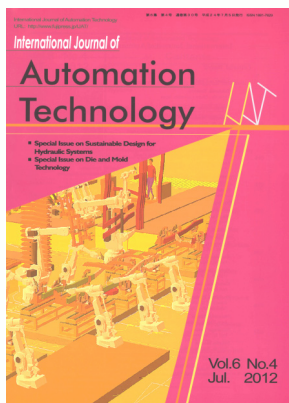
Chemical mechanical planarization/polishing (CMP) is one of the most important processes in the manufacturing of semiconductor devices, and it is being developed and improved continuously each year. CMP has gained prominence in related industries, and its application areas are expanding. From the user's point of view, technical demand is increasing, as are additional applications beyond the semiconductor industry.

This special issue aims to provide researchers the opportunity to access the latest research and practical case studies on recent technologies, including FEOL and BEOL CMP, 3D/TSV, fundamentals of CMP, polishing processes, consumables, equipment, green devices, new applications, metrology, cleaning, defect control, process control, CMP alternatives, SiC, GaN, and sapphire and diamond. Topics of interest in this special issue include, but are not limited to, the following:

- FEOL CMP
- BEOL CMP
- Defects, reliability issues, and post-CMP cleaning
- CMP fundamentals, modeling, and simulation
- Equipment, process control, and metrology
- Emerging and alternative CMP technologies
- CMP consumables
- 3D ICs/TSV/package applications
- CMP for MEMS and hybrid applications
- Substrate polishing, including Si, SiC, GaN, and Diamond

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